IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co–packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Field Stop Technology
- Low Switching Loss Reduces System Power Dissipation
- 10 µs Short Circuit Capability
- Low Gate Charge
- Soft, Fast Free Wheeling Diode
- These are Pb-Free Devices

Typical Applications

- Solar Inverter
- UPS Inverter

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	lc	30 15	A
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	120	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	Ŀ	30 15	А
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	120	Α
Gate-emitter voltage	V_{GE}	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P_{D}	156 62.5	W
Short Circuit Withstand Time $V_{GE} = 15 \text{ V}, V_{CE} = 500 \text{ V}, T_J \le 150^{\circ}\text{C}$	T _{SC}	10	μs
Operating junction temperature range	TJ	–55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

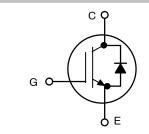
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

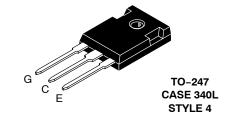


ON Semiconductor®

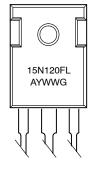
http://onsemi.com

15 A, 1200 V V_{CEsat} = 2.0 V E_{off} = 0.55 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB15N120FLWG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

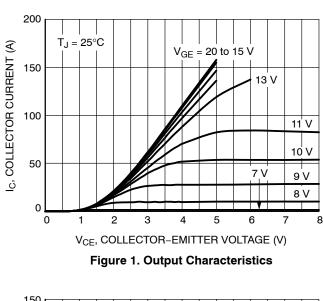
Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.80	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.5	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Parameter Test Conditions		Min	Тур	Max	Unit
STATIC CHARACTERISTIC	•	•		•		1
Collector-emitter breakdown voltage, gate-emitter short-circuited	V_{GE} = 0 V, I_{C} = 500 μ A	V _{(BR)CES}	1200	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 15 A V _{GE} = 15 V, I _C = 15 A, T _J = 150°C	V _{CEsat}	1.5 -	2.0 2.2	2.2	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 150 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 1200 V V _{GE} = 0 V, V _{CE} = 1200 V, T _{J =} 150°C	I _{CES}	- -	- -	0.35 2	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	-	_	100	nA
DYNAMIC CHARACTERISTIC	•	•				•
Input capacitance		C _{ies}	-	3600	-	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	110	-	
Reverse transfer capacitance	7	C _{res}	-	66	-	
Gate charge total		Q_g	-	150	-	nC
Gate to emitter charge	V _{CE} = 600 V, I _C = 15 A, V _{GE} = 15 V	Q _{ge}	-	28	-	
Gate to collector charge		Q _{gc}	-	68	-	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-on delay time		t _{d(on)}	-	72	-	ns
Rise time		t _r	-	19	-	
Turn-off delay time	T _J = 25°C	t _{d(off)}	-	168	=	
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 15 \text{ A}$ $R_{g} = 10 \Omega$	t _f	-	194	=	
Turn-on switching loss	V _{GE} = 0 V/ 15V	E _{on}	-	1.17	=	mJ
Turn-off switching loss		E _{off}	-	0.55	-	
Total switching loss		E _{ts}	-	1.72	=	
Turn-on delay time		t _{d(on)}	-	70	-	ns
Rise time	7	t _r	-	21	-	
Turn-off delay time	T _J = 125°C	t _{d(off)}	-	175	-	
Fall time	$V_{CC} = 600 \text{ V, } I_{C} = 15 \text{ A}$ $R_{c} = 10 \Omega$	t _f	-	310	-	
Turn-on switching loss	$R_g = 10 \Omega$ $V_{GE} = 0 V/ 15V$	E _{on}	-	1.35	-	mJ
Turn-off switching loss	7	E _{off}	-	0.96	-	
Total switching loss		E _{ts}	-	2.31	-	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
DIODE CHARACTERISTIC	•					
Forward voltage	V _{GE} = 0 V, I _F = 15 A V _{GE} = 0 V, I _F = 15 A, T _J = 150°C	V _F	1.5	1.8 2.5	2.2	V
Reverse recovery time	T _J = 25°C	t _{rr}	_	166	-	ns
Reverse recovery charge	$I_F = 15 \text{ A}, V_R = 400 \text{ V}$ di _F /dt = 200 A/μs	Q _{rr}	-	1.1	_	μC
Reverse recovery current		I _{rrm}	-	12	_	Α
Reverse recovery time	T _J = 125°C	t _{rr}	-	200	_	ns
Reverse recovery charge	I _F = 15 A, V _R = 400 V di _F /dt = 200 A/μs	Q _{rr}	_	1.5	_	μC
Reverse recovery current		I _{rrm}	-	15	_	Α



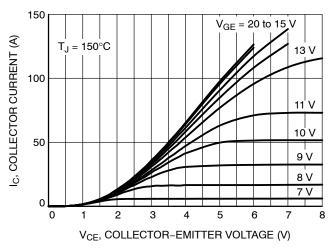


Figure 2. Output Characteristics

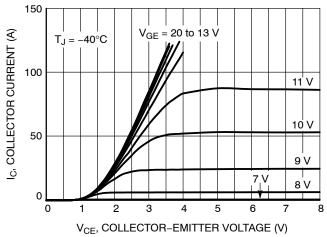


Figure 3. Output Characteristics

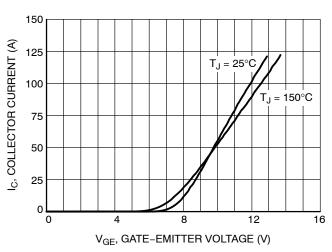


Figure 4. Typical Transfer Characteristics

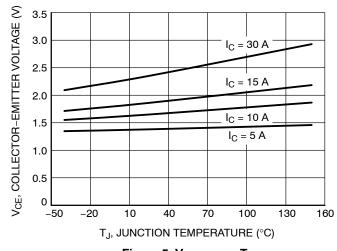


Figure 5. $V_{CE(sat)}$ vs. T_J

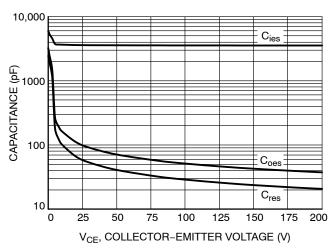


Figure 6. Typical Capacitance

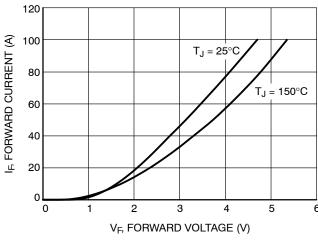


Figure 7. Diode Forward Characteristics

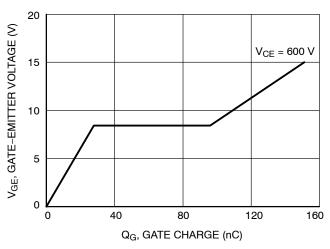


Figure 8. Typical Gate Charge

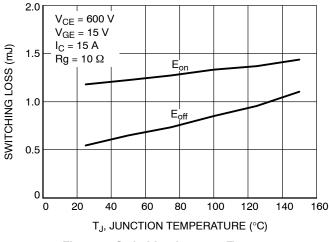


Figure 9. Switching Loss vs. Temperature

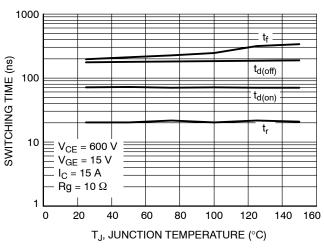


Figure 10. Switching Time vs. Temperature

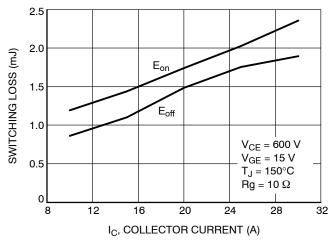


Figure 11. Switching Loss vs. I_C

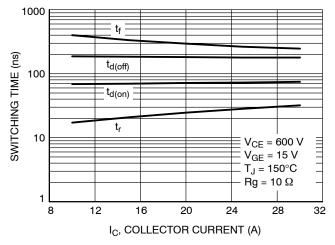
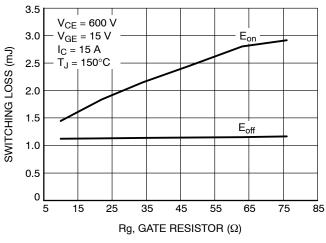


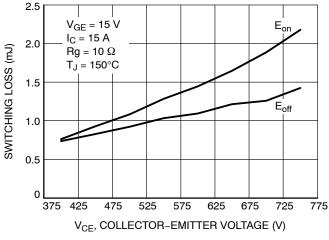
Figure 12. Switching Time vs. I_C



1000 t_{d(off)} t_{f} SWITCHING TIME (ns) $t_{d(on)}$ 100 : t_r 10 V_{CE} = 600 V V_{GE} = 15 V I_C = 15 A $T_{.1} = 150^{\circ}C$ 5 15 25 35 45 55 65 75 85 Rg, GATE RESISTOR (Ω)

Figure 13. Switching Loss vs. Rg

Figure 14. Switching Time vs. Rg



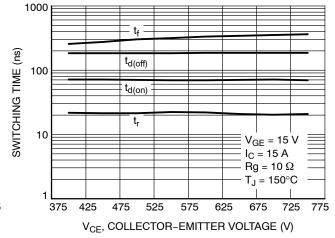
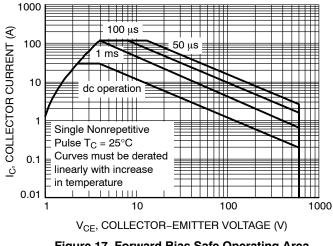


Figure 15. Switching Loss vs. V_{CE}

Figure 16. Switching Time vs. V_{CE}



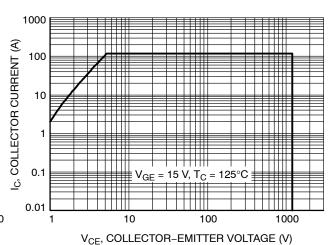


Figure 17. Forward Bias Safe Operating Area

Figure 18. Reverse Bias Safe Operating Area

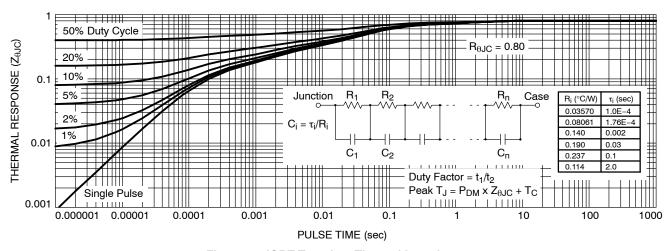


Figure 19. IGBT Transient Thermal Impedance

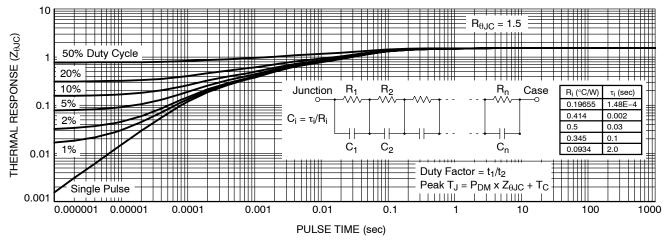


Figure 20. Diode Transient Thermal Impedance

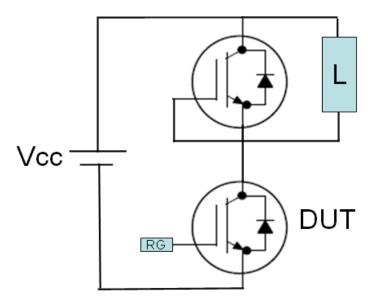


Figure 21. Test Circuit for Switching Characteristics

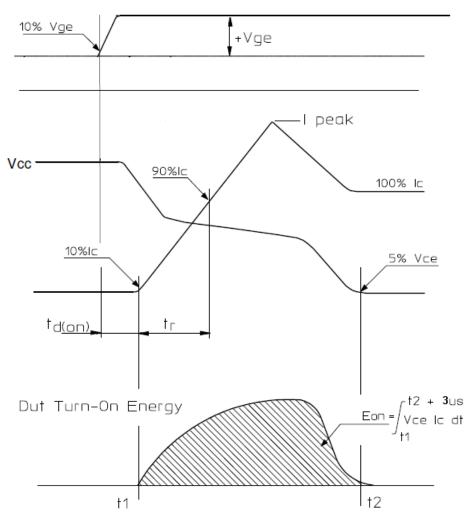


Figure 22. Definition of Turn On Waveform

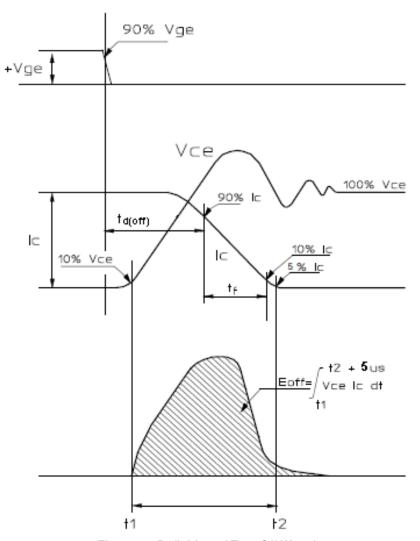
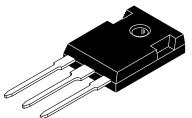


Figure 23. Definition of Turn Off Waveform





TO-247 CASE 340L **ISSUE G**

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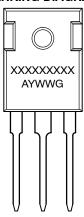
NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER

	MILLIMETERS		INC	HES
DIM	MIN.	MAX.	MIN.	MAX.
Α	20.32	21.08	0.800	0.830
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
Ε	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
Н	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
К	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
Р		4.50		0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242 BSC	
W	2.87	3.12	0.113	0.123

SCALE 1:1	
B B G CO.0253 (0.0253	SEATING PLANE T SEATING PLANE H

GENERIC MARKING DIAGRAM*



STYLE 1: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

PIN 1. CATHODE 2. ANODE

3. GATE 4. ANODE

STYLE 5:

STYLE 2: PIN 1. ANODE 2. CATHODE (S) 3. ANODE 2 4. CATHODES (S)

PIN 1. MAIN TERMINAL 1 2. MAIN TERMINAL 2

3. GATE 4. MAIN TERMINAL 2

STYLE 6:

♦0.25 (0.010)**₩** Y AS

STYLE 3: PIN 1. BASE 2. COLLECTOR 3. EMITTER 4. COLLECTOR STYLE 4: PIN 1. GATE 2. COLLECTOR 3. EMITTER 4. COLLECTOR

XXXXX = Specific Device Code Α = Assembly Location

Υ = Year WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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 VS-CPV364M4KPBF
 NGTB25N120FL2WAG
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 RJH60F3DPQ-A0#T0

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 NGTB75N65FL2WAG
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 IXA40RG1200DHGLB
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 NTE3320
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 APT70GR120J
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 IKZA40N65RH5XKSA1
 IKFW75N65ES5XKSA1
 IKFW50N65ES5XKSA1
 IKFW50N65EH5XKSA1
 IKFW40N65ES5XKSA1

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 IMBG120R220M1HXTMA1
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 IGW75N60H3FKSA1
 HGTG40N60B3
 FGH60N60SMD_F085

 FGH75T65UPD
 STGWA15H120F2
 IKA10N60TXKSA1
 IHW20N120R5XKSA1
 RJH60D2DPP-M0#T2
 IKP20N60TXKSA1

 IHW20N65R5XKSA1
 IDW40E65D2FKSA1